

Number of Components:	Two	Minimum Bond Line Cure Schedule*:	
Mix Ratio By Weight:	10:1	150°C	1 Minute
Specific Gravity:		120°C	5 Minutes
Part A	1.12	100°C	10 Minutes
Part B	1.02	80°C	30 Minutes
Pot Life:	3 Hours		
Shelf Life:	One year at room temperature		

Note: Container(s) should be kept closed when not in use. For filled systems, mix contents of each container (A & B) thoroughly before mixing the two together. *Please see Applications Note available on our website.

Product Description:

EPO-TEK® 353ND-T Black is a two component, high temperature, thixotropic epoxy for fiber optic, PCB and various medical applications.

EPO-TEK® 353ND-T Black Advantages & Application Notes:

- This product is a color-coded, black and opaque version of the industry standard EPO-TEK® 353ND-T epoxy adhesive.
- Suggested applications:
 - Semiconductor, glob top DAM around IC's, using COB or DCA packaging formats
 - Electronics Assembly
 - Insulating adhesive for bonding stainless steel metals, ceramics and carbon composites used in ink-jetting heads
 - Insulating and plugging wires and feed-through cables of automotive circuits
 - Hard Disk Drive – thixotropic staking and termination of Al and Cu coils
 - Adhesive for brushless motors and Cu coil windings
 - Medical
 - Light blocking in endoscopes, camera optics and IR sensor devices
 - Optical
 - Fiber optic component packaging: bonding fibers, active optics, metals, ceramics and plastic
- Available in alternative viscosities and color. Contact techserv@epotek.com for your best recommendation.

Typical Properties: (To be used as a guide only, not as a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results; Cure condition: 150°C/1 hour; * denotes test on lot acceptance basis)

Physical Properties:	
*Color: Part A: Black Part B: Amber	Die Shear Strength @ 23°C: ≥ 15 Kg / 5,100 psi
*Consistency: Smooth thixotropic paste	Degradation Temp. (TGA): 409°C
*Viscosity (@ 20 RPM/23°C): 9,000 – 15,000 cPs	Weight Loss:
Thixotropic Index: 3.8	@ 200°C: 0.53%
*Glass Transition Temp.(Tg): ≥ 90°C (Dynamic Cure 20—200°C /ISO 25 Min; Ramp -10—200°C @ 20°C/Min)	@ 250°C: 1.22%
Coefficient of Thermal Expansion (CTE):	@ 300°C: 2.37%
Below Tg: 43 x 10 ⁻⁶ in/in/°C	Operating Temp:
Above Tg: 231 x 10 ⁻⁶ in/in/°C	Continuous: - 55°C to 225°C
Shore D Hardness: 80	Intermittent: - 55°C to 325°C
Lap Shear Strength @ 23°C: > 2,000 psi	Storage Modulus @ 23°C: 559,120 psi
	*Particle Size: ≤ 20 Microns
Optical Properties @ 23°C:	
Index of Refraction @ 23°C: N/A	Spectral Transmission @ 23°C: < 5 % @ 300-1460 nm < 7 % @ 1550 nm
Electrical & Thermal Properties:	
Thermal Conductivity: N/A	Volume Resistivity @ 23°C: ≥ 4 x 10 ¹² Ohm-cm
Dielectric Constant (1KHz): 3.21	Dissipation Factor (1KHz): 0.003

Polytec PT GmbH Polymere Technologien
Polytec-Platz 1-7 76337 Waldbronn Tel.: 0049 7243 604 400 E-mail: info@polytec-pt.de
www.polytec-pt.de

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

Für weitere Auskünfte stehen Ihnen unsere Anwendungstechniker gerne unter Tel. (+49) 07243-604-400 oder per E-mail: info@polytec-pt.de zur Verfügung.

Zur Beachtung:

Vorstehende Angaben können nur allgemeine Hinweise sein. Bei den aufgeführten Eigenschaften und Leistungsmerkmalen handelt es sich um circa-Werte, diese sind nicht Teil der Produktspezifikation. Wegen der außerhalb unseres Einflusses liegenden Verarbeitungs- und Anwendungsbedingungen und der Vielzahl unterschiedlicher Materialien empfehlen wir, in jedem Fall zunächst ausreichende Eigenversuche durchzuführen. Eine Haftung für konkrete Anwendungsergebnisse kann daher aus den Angaben und Hinweisen in diesem Merkblatt nicht abgeleitet werden.

Mit Erscheinen dieser Ausgabe verlieren alle vorhergehenden technischen Merkblätter Ihre Gültigkeit. Sicherheitsrelevante Daten können dem Sicherheitsdatenblatt entnommen werden.

Änderungen vorbehalten / Stand: 07/2010